



# Product Change Notification

**Change Notification #:** 116943 - 00  
**Change Title:** Select Intel® SSD 660p Series Products, PCN 116943-00, Transport Media, Documentation, Packaging change and Warranty booklet update  
**Date of Publication:** May 15, 2019

## Key Characteristics of the Change:

Transport Media, Documentation

## Forecasted Key Milestones:

<b>Date Customer Must be Ready to Receive Post-Conversion Material:</b>	May 31, 2019
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## Description of Change to the Customer:

The Intel® SSD 660p Series SKUs listed in the products affected table below will undergo the following changes:

1. Packaging kit will be updated to a new carton box to improve handling and reduce risk of damaged carton flaps/lock tabs.
2. The Warranty booklet EU Single Point of Contact address is changing. It will be updated with the following address:

Current:	EU Single Point of Contact: Intel Corporation (UK) Ltd. Attn: Corp. Quality Pipers Way Swindon, Wiltshire SN3 1RJ UK
New:	EU Single Point of Contact: Intel Deutschland GmbH Attn: Corp. Quality Am Campeon 10-12, 85579 Neubiberg, Germany

## Customer Impact of Change and Recommended Action:

These updates will not affect the Form, Fit, or Function of the products.

Customer should be aware of these packaging changes and take any steps for incoming and processing to accommodate the new packages.

Intel will attempt to deplete pre-conversion material before shipping post-conversion material but there is a possibility of Intel shipping mixed inventory. Therefore, customers will need to manage and migrate to the post-conversion material as soon as possible.

Milestone dates are estimates and subject to change based on business and operational conditions.

Please contact your local Intel Field Sales Rep if you have any further questions about these changes.

## Products Affected / Intel Ordering Codes:

Marketing Name	Product Code	MM#
Intel® SSD 660p Series (512GB, M.2 80mm PCIe 3.0 x4, 3D2, QLC)	SSDPEKNW512G8X1	978348
Intel® SSD 660p Series (512GB, M.2 80mm PCIe 3.0 x4, 3D2, QLC)	SSDPEKNW512G8XT	978349
Intel® SSD 660p Series (1.0TB, M.2 80mm PCIe 3.0 x4, 3D2, QLC)	SSDPEKNW010T8X1	978350
Intel® SSD 660p Series (2.0TB, M.2 80mm PCIe 3.0 x4, 3D2, QLC)	SSDPEKNW020T8X1	978351
Intel® SSD 660p Series (2.0TB, M.2 80mm PCIe 3.0 x4, 3D2, QLC)	SSDPEKNW020T8XT	984872
Intel® SSD 660p Series (1.0TB, M.2 80mm PCIe 3.0 x4, 3D2, QLC)	SSDPEKNW010T8XT	984875

## PCN Revision History:

**Date of Revision:**

May 15, 2019

**Revision Number:**

00

**Reason:**

Originally Published PCN



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**Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.**

**Americas Contact:** [asmo.pcn@intel.com](mailto:asmo.pcn@intel.com)

**Asia Pacific/PRC Contact:** [apagccb@intel.com](mailto:apagccb@intel.com)

**Europe Email:** [eccb@intel.com](mailto:eccb@intel.com)

**Japan Email:** [jccb.ijkk@intel.com](mailto:jccb.ijkk@intel.com)

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